

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

- Claim 1 (currently amended): An integrated circuit package, having central leads comprising:**
- 5 a substrate having an upper surface, a lower surface and a long slot penetrating from the upper surface to the lower surface, wherein the lower surface is forming formed with a wiring regions arranged at the two sides one side of the long slot, and the wiring regions is formed forming with a plurality of connected connection points, and a the length of the wiring regions are is smaller than a length of the long slot of the substrate;
- 10 a resistant layer⁴², which is coated on and in contact with the lower surface⁵⁴ of the substrate⁴⁰, and is located between the long slot⁵⁶ and the wiring region⁵⁸, wherein the resistant layer separates the long slot from the wiring region, and a length of the resistant layer is substantially equal to the length of the wiring region;
- 15 a glue layer being coated on the upper surface of the substrate and being located at the a periphery of the long slot;
- 20 an integrated circuit having a first surface forming formed with a plurality of bonding pads and a second surface, the first surface being adhered to the glue layer, then the bonding pads being exposed from the long slot of the substrate;
- 25 a plurality of wires, each of which is arranged within the long slot of the substrate and is electrically connects connected the bonding pad of the integrated circuit to the connected connection point of the substrate; and
- 30 a first compound layer being filled within the long slot of the substrate for protecting to protect the each wires.

Claim 2 (cancelled).

- Claim 3 (currently amended): The integrated circuit package having central leads according to claim 1, wherein the connected connection points of the lower surface of the substrate is are formed with a ball grid array (BGA).**

Claim 4 (currently amended): The integrated circuit package ~~having central~~ leads according to claim 1, wherein further ~~comprises comprising~~ a second compound layer, which ~~is covered on~~ covers the upper surface of the substrate.